- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

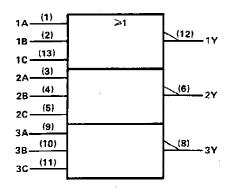
These devices contain three independent 3-input NOR gates.

The SN5427 and SN54LS27 are characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to 125 $^{\circ}\text{C}$. The SN7427 and SN74LS27 are characterized for operation from 0 $^{\circ}\text{C}$ to 70 $^{\circ}\text{C}$.

FUNCTION TABLE (each gate)

	NPUT	s	OUTPUT
Α	В	С	Y
Н	х	x	Ļ
Х	Н	х	L
X	Х	Н	L
L	L	L	н

logic symbol†



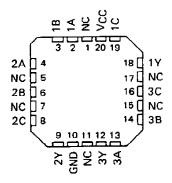
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN5427, SN54LS27...J OR W PACKAGE SN7427...N PACKAGE SN74LS27...D OR N PACKAGE (TOP VIEW)

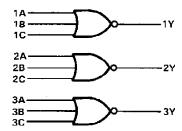
1Α 🗖	1	U14 D VCC
1B 🗖	2	13 <u> </u>] 1C
2A 🗆	3	12] 1Y
2B 🗖	4	11D 3C
2C 🗖	5	10 3B
2Y 🗖	6	9 🛚 3A
GND 🗖	7	8 🗖 3 Y

SN54LS27 . . . FK PACKAGE (TOP VIEW)



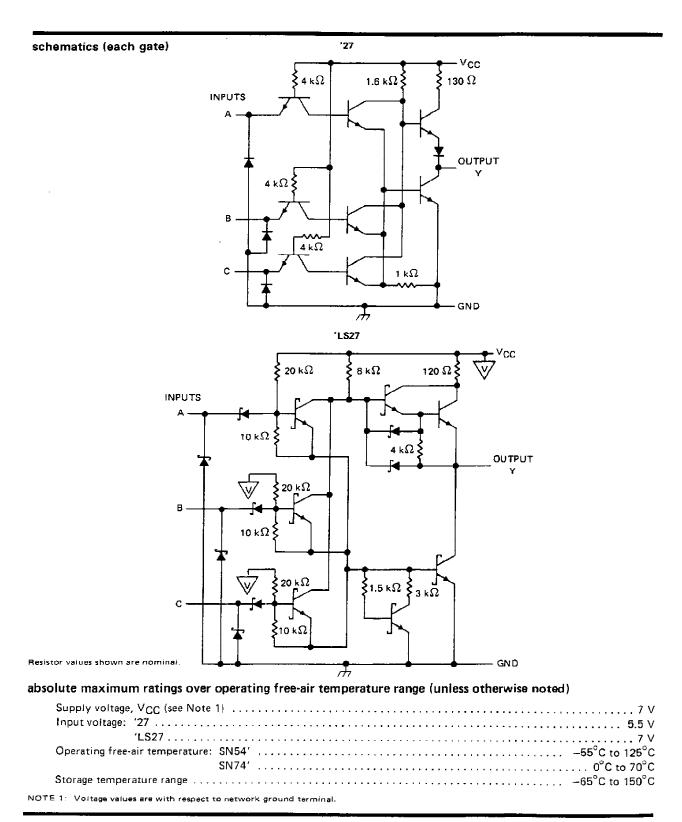
NC - No internal connection

logic diagram



positive logic

 $Y = \overline{A + B + C}$ or $Y = \overline{A \cdot B \cdot C}$



recommended operating conditions

			SN5427				UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VGC	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
V_{IH}	High-level input voltage	2	•		2			٧
VIL	Low-level input voltage			8,0			0.8	٧
Іон	High-level output current			- 0.8			- 0.8	mΑ
lo L	Low-level output current			16			16	mΑ
TA	Operating free-air temperature	- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	-	TEST CONDIT	TIONS +		SN5427	,		SN7427	,	
FANAMETER		rest conditi	TIONS	MIN	TYP ‡	MAX	MIN	TYP ‡	MAX	UNIT
Vικ	V _{CC} = MIN,	I ₁ = - 12 mA				- 1.5			- 1.5	٧
٧ОН	V _{CC} = MIN,	V _{IL} = 0.8 V,	I _{OH} = -0.8 mA	2.4	3.4		2.4	3.4	i	V
۷٥٢	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	٧
l _I	V _{CC} = MAX,	V ₁ = 5.5 V				1			1	mA
ήн	V _{CC} = MAX,	V ₁ = 2.4 V			•	40			40	μΑ
կլ	VCC = MAX,	V1 = 0.4 V				- 1.6			- 1.6	mΑ
los §	V _{CC} = MAX			- 20		- 55	- 18		- 55	mA
ІССН	VCC = MAX,	VI = 0 V	 		10	16		10	16	mA
^I CCL	V _{CC} = MAX,	See Note 2			16 ,	26		16	26	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, VCC = 5 V, TA = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONI	OITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	A, B or C	v	R _L = 400 Ω,	C _L = 15 pF		10	15	ns
tpHL	A, B UI C	,	11[- 400 32,	C[- 10 h		7	11	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time.

SN54LS27, SN74LS27 TRIPLE 3-INPUT POSITIVE-NOR GATES

recommended operating conditions

•		S	SN54LS27			SN74LS27			
_		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			٧	
VIL	Low-level input voltage			0.7			0.8	٧	
Іон	High-level output current			- 0.4			- 0.4	mΑ	
loL	Low-level output current			4			В	mA	
TΑ	Operating free-air temperature	– 55		125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS †				27	S	N74LS2	7	LINIZT
PARAMETER		TEST CONDI	HOM2 T	MIN	TYP‡	MAX	MIN	TYP ‡	MAX	TINU
۷ıĸ	V _{CC} = MIN,	I _I = - 18 mA				– 1.5			– 1.5	>
Voн	V _{CC} - MIN,	V _{IL} = MAX,	I _{OH} = − 0.4 mA	2.5	3.4		2.7	3.4		٧
.,	VCC = MIN,	V _{1H} = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	v
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	IOL = 8 mA					0.35	0.5	
l _l	V _{CC} = MAX,	V ₁ = 7 V				0.1			0.1	mA
ин	VCC = MAX,	V ₁ = 2.7 V				20			20	μΑ
l(L	V _{CC} = MAX,	V ₁ = 0.4 V	*			- 0.4			0.4	mA
IOS §	V _{CC} = MAX			- 20		- 100	20		- 100	mA
Іссн	V _{CC} = MAX.	V _I = 0 V			2	4		2	4	mΑ
lccr	VCC = MAX.	See Note 2			3.4	6.8		3.4	6.8	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	IDITIONS	MIN	TYP	MAX	UNIT
tPLH	A B == C	,	R _L = 2 kΩ,	C ₁ = 15 pF		10	15	пѕ
t _{PHL}	A, B or C	, 	n 2 ksz,	C[- 15 pF		10	15	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/30302B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30302B2A	Samples
JM38510/30302BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30302BCA	Samples
JM38510/30302BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30302BCA	Samples
JM38510/30302BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30302BDA	Samples
JM38510/30302BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30302BDA	Samples
M38510/30302B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30302B2A	Samples
M38510/30302B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30302B2A	Samples
M38510/30302BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30302BCA	Samples
M38510/30302BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30302BCA	Samples
M38510/30302BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30302BDA	Samples
M38510/30302BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30302BDA	Samples
SN54LS27J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS27J	Samples
SN54LS27J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS27J	Samples
SN74LS27D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS27	Samples
SN74LS27D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS27	Samples
SN74LS27DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS27	Samples
SN74LS27DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS27	Samples



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS27N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS27N	Samples
SN74LS27N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS27N	Samples
SN74LS27NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS27	Samples
SN74LS27NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS27	Samples
SNJ54LS27FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 27FK	Samples
SNJ54LS27FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 27FK	Samples
SNJ54LS27J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS27J	Samples
SNJ54LS27J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS27J	Samples
SNJ54LS27W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS27W	Samples
SNJ54LS27W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS27W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: Til defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet J\$709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

PACKAGE OPTION ADDENDUM

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(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS27, SN74LS27:

Catalog: SN74LS27

Military: SN54LS27

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS27DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS27NSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS27DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LS27NSR	SO	NS	14	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/30302B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
JM38510/30302BDA	W	CFP	14	1	506.98	26.16	6220	NA
M38510/30302B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/30302BDA	W	CFP	14	1	506.98	26.16	6220	NA
SN74LS27D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS27N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS27N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS27FK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54LS27W	W	CFP	14	1	506.98	26.16	6220	NA

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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